

LOCTITE ECCOBOND FP4322

July 2018

PRODUCT DESCRIPTION

LOCTITE ECCOBOND FP4322 provides the following product characteristics:

Technology	Epoxy
Appearance	Black
Cure	Heat cure
Application	Semiconductor, Encapsulant

LOCTITE ECCOBOND FP4322 is a high purity liquid epoxy encapsulant designed for semiconductor encapsulation. It is a high flow material which requires a cavity of flow control barrier to prevent excessive flow.

LOCTITE ECCOBOND FP4322 is suitable for encapsulating bare chips mounted to plastic substrates as well as potting of small hybrid circuit modules. Spot encapsulation of bare chips on ceramic substrates is not suggested in most cases.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, Brookfield - RVF, 25 °C, mPa·s (cP):	
Spindle 7, speed 2 rpm	92,500
Spindle 7, speed 20 rpm	52,500
Specific Gravity @ 25 °C	1.69
Filler Content, %	65
Pot Life @ 25 °C (time to double viscosity), days	1
Shelf Life, days:	
@ 25°C	2
@ -40°C	120
Flash Point - See SDS	

TYPICAL CURING PERFORMANCE

Gel Time

Gel Time @ 121 °C, minutes 11

Recommended Cure Schedule

2 to 3 hours @ 170°C or 3 to 6 hours @ 150°C

Alternate Cure Schedule

1 hour @ 125°C plus 4 hours @ 150°C

The recommended alternate cure schedule is designed for packages which are effected by high levels of stress.

A two-step cure will minimize stress and warpage on large substrates. Curing below 140°C is not recommended. User should gel devices immediately after dispensing to prevent moisture degradation of ultimate cure properties. Use suggested cure schedules as general guidelines; other cure schedules may yield satisfactory results.

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties:

Hardness, Shore D	97
Glass Transition Temperature (Tg), °C	160
Coefficient of Thermal Expansion, in/in/°C:	
@ 40 to 120°C	30×10 ⁻⁶
Density, gm/cc	1.7
Linear Shrinkage, %	0.43
Extractable Ionic Content, ppm:	
Chloride (Cl-)	25
Potassium (K+)	25
Sodium (Na+)	25
Moisture Absorption, 9 hour immersion @ 100 %	0°C, 0.25

Electrical Properties:

Volume Resistivity, ohms-cm	6.2×10 ¹⁴
Surface Resistivity, ohms	1.6×10 ¹⁴
Dielectric Constant / Dissipation Factor @ 25°C:	
@ 1 KHz	3.18/0.005
@ 10 KHz	3.15/0.006
@ 100 KHz	3.04/0.11

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

DIRECTIONS FOR USE

- 1. Warm at room temperature until no longer cool to the touch (normally 20-60 minutes).
- 2. Do not thaw in an oven or water bath.
- For best results LOCTITE ECCOBOND FP4322 should be dispensed onto a substrate warmed to approximately 90°C. This will help minimize air entrapment under bonding wire.



STORAGE

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40 °C.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in psi x 145 = N/mm² MPa = N/mm² N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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